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FQD4P25TM-WS

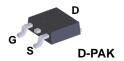
P-Channel QFET® MOSFET -250 V, -3.1 A, 2.1 Ω

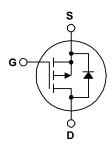
Description

This P-Channel enhancement mode power MOSFET is produced using ON Semiconductor Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide • Improved dv/dt Capability superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- -3.1 A, -250 V, $R_{DS(on)}$ = 2.1 Ω (Max.) @ V_{GS} = 10 V, $I_D = -1.55 A$
- Low Gate Charge (Typ. 10 nC)
- Low Crss (Typ. 10.3 pF)
- 100% Avalanche Tested
- · RoHS Compliant





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQD4P25TM-WS	Unit
V _{DSS}	Drain-Source Voltage		-250	V
I _D	Drain Current - Continuous (T _C = 25°C)		-3.1	Α
	- Continuous (T _C = 100°C)		-1.96	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	-12.4	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	280	mJ
I _{AR}	Avalanche Current	(Note 1)	-3.1	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W
	Power Dissipation (T _C = 25°C)		45	W
	- Derate above 25°C		0.36	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FQD4P25TM-WS	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.		
В	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	110	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	50	

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQD4P25TM-WS	FQD4P25S	DPAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics

T_C = 25°C unless otherwise noted.

Parameter	Test Conditions	Min.	Тур.	Max.	Unit
racteristics					
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-250			V
Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-0.21		V/°C
Zara Cata Valtaga Drain Current	V _{DS} = -250 V, V _{GS} = 0 V			-1	μΑ
Zero Gate Voltage Drain Current	V _{DS} = -200 V, T _C = 125°C			-10	μΑ
Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
	Drain-Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate-Body Leakage Current, Forward	$ \begin{array}{llllllllllllllllllllllllllllllllllll$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	tracteristics Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}$, $I_D = -250 \text{ μA}$ -250 Breakdown Voltage Temperature Coefficient $I_D = -250 \text{ μA}$, Referenced to 25°C -0.21 Zero Gate Voltage Drain Current $V_{DS} = -250 \text{ V}$, $V_{GS} = 0 \text{ V}$ $V_{DS} = -200 \text{ V}$, $V_{CS} = 125°C$ Gate-Body Leakage Current, Forward $V_{GS} = -30 \text{ V}$, $V_{DS} = 0 \text{ V}$	tracteristicsDrain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = -250 \text{ μA}$ $-250 $ $$ Breakdown Voltage Temperature Coefficient $I_D = -250 \text{ μA}, \text{ Referenced to } 25^{\circ}\text{C}$ $$ $-0.21 $ Zero Gate Voltage Drain Current $V_{DS} = -250 \text{ V}, V_{GS} = 0 \text{ V}$ $$ $$ -1 $V_{DS} = -200 \text{ V}, T_C = 125^{\circ}\text{C}$ $$ $$ -10 Gate-Body Leakage Current, Forward $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$ $$ $$ -100

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -1.55 \text{ A}$		1.63	2.1	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = -40 \text{ V}, I_{D} = -1.55 \text{ A}$		2.0		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -25 V, V _{GS} = 0 V,	 325	420	pF
Coss	Output Capacitance	f = 1.0 MHz	 65	85	pF
C _{rss}	Reverse Transfer Capacitance		 10	13	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = -125 V, I _D = -4.0 A,	 9.5	30	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 60	130	ns
t _{d(off)}	Turn-Off Delay Time		 14	40	ns
t _f	Turn-Off Fall Time	(Note 4)	 27	65	ns
Q_g	Total Gate Charge	V _{DS} = -200 V, I _D = -4.0 A,	 10.3	14	nC
Q _{gs} Q _{gd}	Gate-Source Charge	V _{GS} = -10 V	 2.7		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 5.2		nC

Drain-Source Diode Characteristics and Maximum Ratings

Diam	Diam Cource Dious Characteriotics and maximum ratings						
I _S	Maximum Continuous Drain-Source Diode Forward Current				-3.1	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				-12.4	Α	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -3.1 A			-5.0	V	
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -4.0 \text{ A,}$		140		ns	
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		0.64		μС	

- Notes: 1. Repetitive rating : pulse-width limited by maximum Hunction temperature. 2. L = 46.6 mH, I_{AS} = -3.1 A, V_{DD} = -50V, R_G = 25 Ω , starting T_J = 25°C. 3. I_{SD} \leq -4.0 A, dIVdt \leq 300 AV_{IIS}, V_{DD} \leq BV_{DSS}, starting T_J = 25°C .

- 4. Essentially independent of operating temperature.

Typical Characteristics

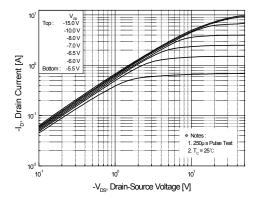


Figure 1. On-Region Characteristics

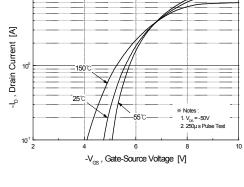


Figure 2. Transfer Characteristics

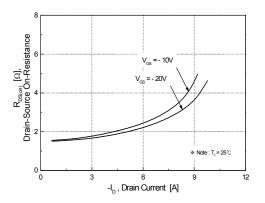


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

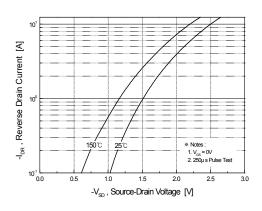


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

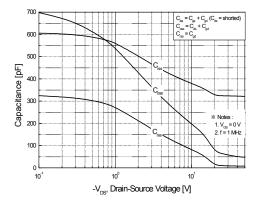


Figure 5. Capacitance Characteristics

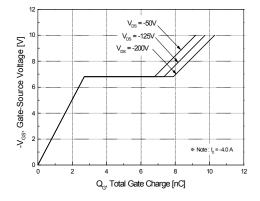
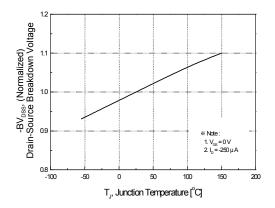


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)



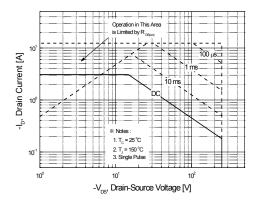
3.0

Output

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Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



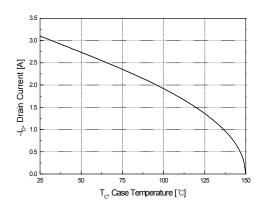


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

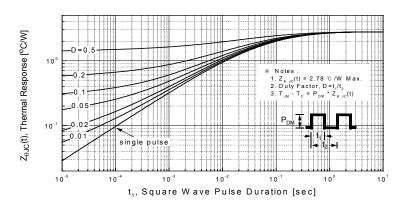


Figure 11. Transient Thermal Response Curve

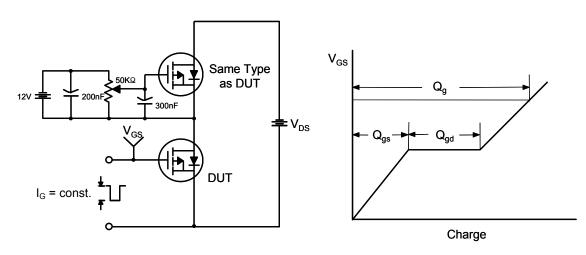


Figure 12. Gate Charge Test Circuit & Waveform

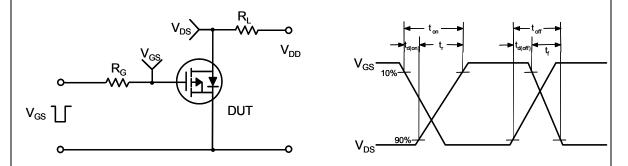


Figure 13. Resistive Switching Test Circuit & Waveforms

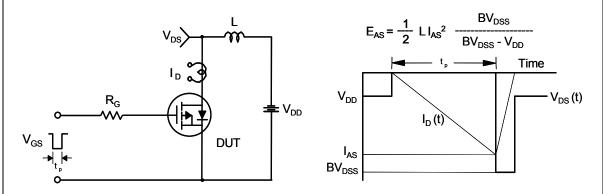
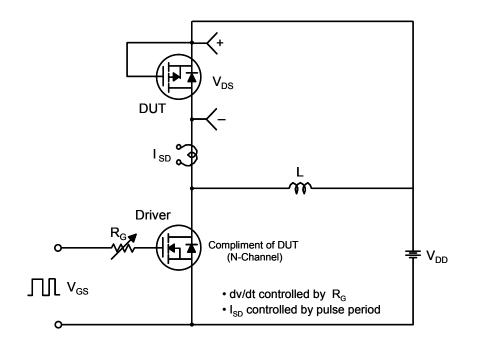


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



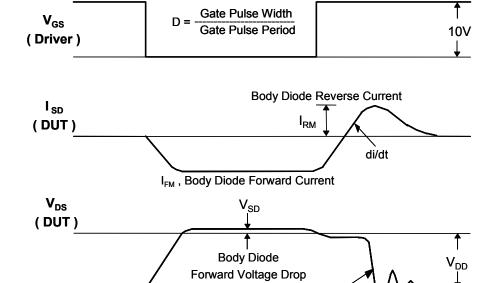


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Body Diode Recovery dv/dt

Mechanical Dimensions

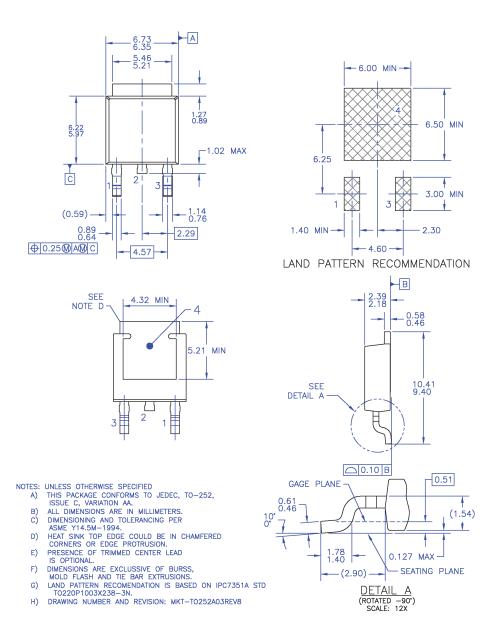


Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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